

ABSTRACT OF THE DISCLOSURE

A semiconductor device includes: a substrate on which is formed an interconnecting pattern; a first semiconductor chip provided above the substrate and having a first electrode on a surface facing the substrate; and a second semiconductor chip provided above the first semiconductor chip and having a second electrode on a surface facing the substrate. The substrate has a bent portion inclined from the first electrode to the second electrode. The interconnecting pattern extends along the bent portion and electrically connected to the first and second electrodes.